Data sheet acquired from Cypress Semiconductor Corporation.
Data sheet modified to remove devices not offered.

CY74FCT16373T
CY74FCT162373T

16-Bit Latches

SCCS054C - August 1994 - Revised October 2003

Features

- **I_{off} supports partial-power-down mode operation**
- **Edge-rate control circuitry for significantly improved noise characteristics**
- **Typical output skew < 250 ps**
- **ESD > 2000V**
- **TSSOP (19.6-mil pitch) and SSOP (25-mil pitch) packages**
- **Industrial temperature range of −40˚C to +85˚C**
- **V_{CC} = 5V ± 10%**

CY74FCT16373T Features:

- **64 mA sink current, 32 mA source current**
- **Typical V_{OLP} (ground bounce) <1.0V at V_{CC} = 5V, T_A = 25˚C**

CY74FCT162373T Features:

- **Balanced 24 mA output drivers**
- **Reduced system switching noise**
- **Typical V_{OLP} (ground bounce) <0.6V at V_{CC} = 5V, T_A= 25˚C**

Functional Description

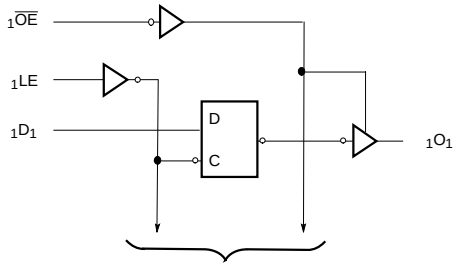
CY74FCT16373T and CY74FCT162373T are 16-bit D-type latches designed for use in bus applications requiring high speed and low power. These devices can be used as two independent 8-bit latches or as a single 16-bit latch by connecting the Output Enable ($\overline{OE}$) and Latch (LE) inputs. Flow-through pinout and small shrink packaging aid in simplifying board layout.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

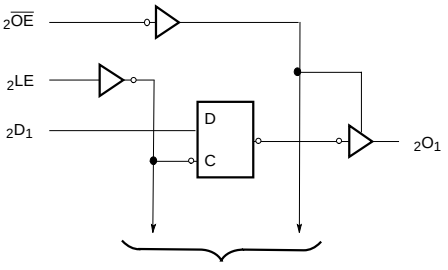
The CY74FCT16373T is ideally suited for driving high-capacitance loads and low-impedance backplanes.

The CY74FCT162373T has 24-mA balanced output drivers with current limiting resistors in the outputs. This reduces the need for external terminating resistors and provides for minimal undershoot and reduced ground bounce. The CY74FCT162373T is ideal for driving transmission lines.

Logic Block Diagrams



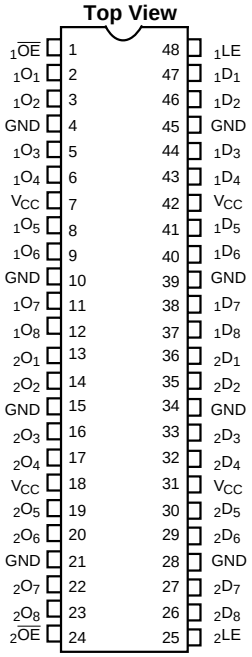
FCT162373-1



FCT162373-2

Pin Configuration

SSOP/TSSOP/TVSOP
Top View



FCT162373-3

Copyright © 2003, Texas Instruments Incorporated

Pin Description

Name	Description
D	Data Inputs
LE	Latch Enable Inputs (Active HIGH)
$\overline{OE}$	Output Enable Inputs (Active LOW)
O	Three-State Outputs

Function Table[1]

Inputs			Outputs
D	**LE**	**$\overline{OE}$**	**O**
H	H	L	H
L	H	L	L
X	L	L	Q_0
X	X	H	Z

Maximum Ratings[2, 3]

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature ..... Com'l –55°C to +125°C

Ambient Temperature with Power Applied ..... Com'l –55°C to +125°C

DC Input Voltage .....–0.5V to +7.0V

DC Output Voltage .....–0.5V to +7.0V

DC Output Current (Maximum Sink Current/Pin) .....–60 to +120 mA

Power Dissipation 1.0W

Static Discharge Voltage.....>2001V (per MIL-STD-883, Method 3015)

Operating Range

Range	Ambient Temperature	V_{CC}
Industrial	–40°C to +85°C	5V ± 10%

Electrical Characteristics Over the Operating Range

Parameter	Description	Test Conditions	Min.	Typ.[4]	Max.	Unit
V_{IH}	Input HIGH Voltage		2.0			V
V_{IL}	Input LOW Voltage				0.8	V
V_H	Input Hysteresis[5]			100		mV
V_{IK}	Input Clamp Diode Voltage	V_{CC}=Min., I_{IN}=–18 mA		–0.7	–1.2	V
I_{IH}	Input HIGH Current	V_{CC}=Max., V_I=V_{CC}			±1	µA
I_{IL}	Input LOW Current	V_{CC}=Max., V_I=GND			±1	µA
I_{OZH}	High Impedance Output Current (Three-State Output pins)	V_{CC}=Max., V_{OUT}=2.7V			±1	µA
I_{OZL}	High Impedance Output Current (Three-State Output pins)	V_{CC}=Max., V_{OUT}=0.5V			±1	µA
I_{OS}	Short Circuit Current[6]	V_{CC}=Max., V_{OUT}=GND	–80	–140	–200	mA
I_O	Output Drive Current[6]	V_{CC}=Max., V_{OUT}=2.5V	–50		–180	mA
I_{OFF}	Power-Off Disable	V_{CC}=0V, V_{OUT}≤4.5V[7]			±1	µA

Output Drive Characteristics for CY74FCT16373T

Parameter	Description	Test Conditions	Min.	Typ.[4]	Max.	Unit
V_{OH}	Output HIGH Voltage	V_{CC}=Min., I_{OH}=–3 mA	2.5	3.5		V
		V_{CC}=Min., I_{OH}=–15 mA	2.4	3.5		V
		V_{CC}=Min., I_{OH}=–32 mA	2.0	3.0		V
V_{OL}	Output LOW Voltage	V_{CC}=Min., I_{OL}=64 mA		0.2	0.55	V

Notes:

1. H = HIGH Voltage Level. L = LOW Voltage Level. X = Don't Care. Z = High Impedance. Q_0=Previous state of flip-flop.
2. Operation beyond the limits set forth may impair the useful life of the device. Unless otherwise noted, these limits are over the operating free-air temperature range.
3. Unused inputs must always be connected to an appropriate logic voltage level, preferably either V_{CC} or ground.
4. Typical values are at V_{CC}=5.0V, T_A= +25˚C ambient.
5. This parameter is specified but not tested.
6. Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample and hold techniques are preferable in order to minimize internal chip heating and more accurately reflect operational values. Otherwise prolonged shorting of a high output may raise the chip temperature well above normal and thereby cause invalid readings in other parametric tests. In any sequence of parameter tests, I_{OS} tests should be performed last.
7. Tested at +25˚C.

Output Drive Characteristics for CY74FCT162373T

Parameter	Description	Test Conditions	Min.	Typ.[4]	Max.	Unit
I_{ODL}	Output LOW Current[6]	V_{CC}=5V, V_{IN}=V_{IH} or V_{IL}, V_{OUT}=1.5V	60	115	150	mA
I_{ODH}	Output HIGH Current[6]	V_{CC}=5V, V_{IN}=V_{IH} or V_{IL}, V_{OUT}=1.5V	–60	–115	–150	mA
V_{OH}	Output HIGH Voltage	V_{CC}=Min., I_{OH}=–24 mA	2.4	3.3		V
V_{OL}	Output LOW Voltage	V_{CC}=Min., I_{OL}=24 mA		0.3	0.55	V

Capacitance[5] (T_A = +25°C, f = 1.0 MHz)

Parameter	Description	Test Conditions	Typ.[4]	Max.	Unit
C_{IN}	Input Capacitance	V_{IN} = 0V	4.5	6.0	pF
C_{OUT}	Output Capacitance	V_{OUT} = 0V	5.5	8.0	pF

Power Supply Characteristics

Parameter	Description	Test Conditions		Typ.[4]	Max.	Unit
I_{CC}	Quiescent Power Supply Current	V_{CC}=Max.	V_{IN}≤0.2V, V_{IN}≥V_{CC}–0.2V	5	500	µA
ΔI_{CC}	Quiescent Power Supply Current (TTL inputs HIGH)	V_{CC}=Max.	V_{IN}=3.4V[8]	0.5	1.5	mA
I_{CCD}	Dynamic Power Supply Current[9]	V_{CC}=Max., One Input Toggling, 50% Duty Cycle, Outputs Open, $\overline{OE}$=GND	V_{IN}=V_{CC} or V_{IN}=GND	60	100	µA/MHz
I_C	Total Power Supply Current[10]	V_{CC}=Max., f_1=10 MHz, 50% Duty Cycle, Outputs Open, One Bit Toggling, $\overline{OE}$=GND, LE=V_{CC}	V_{IN}=V_{CC} or V_{IN}=GND	0.6	1.5	mA
			V_{IN}=3.4V or V_{IN}=GND	0.9	2.3	mA
		V_{CC}=Max., f_1=2.5 MHz, 50% Duty Cycle, Outputs Open, Sixteen Bits Toggling, $\overline{OE}$=GND, LE=V_{CC}	V_{IN}=V_{CC} or V_{IN}=GND	2.4	4.5[11]	mA
			V_{IN}=3.4V or V_{IN}=GND	6.4	16.5[11]	mA

Notes:

8. Per TTL driven input (V_{IN}=3.4V); all other inputs at V_{CC} or GND.
9. This parameter is not directly testable, but is derived for use in Total Power Supply calculations.
10. I_C= $I_{QUIESCENT}$ + I_{INPUTS} + $I_{DYNAMIC}$
    I_C = I_{CC}+$\Delta I_{CC} D_H N_T$+$I_{CCD}(f_0/2 + f_1 N_1)$
    I_{CC} = Quiescent Current with CMOS input levels
    ΔI_{CC} = Power Supply Current for a TTL HIGH input(V_{IN}=3.4V)
    D_H = Duty Cycle for TTL inputs HIGH
    N_T = Number of TTL inputs at D_H
    I_{CCD} = Dynamic Current caused by an input transition pair (HLH or LHL)
    f_0 = Clock frequency for registered devices, otherwise zero
    f_1 = Input signal frequency
    N_1 = Number of inputs changing at f_1
    All currents are in milliamps and all frequencies are in megahertz.
11. Values for these conditions are examples of the I_{CC} formula. These limits are specified but not tested.

Switching Characteristics Over the Operating Range[12]

Parameter	Description	CY74FCT16373AT CY74FCT162373AT		Unit	Fig. No.[13]
		Min.	Max.		
t_{PLH} t_{PHL}	Propagation Delay D to O	1.5	5.2	ns	1, 3
t_{PLH} t_{PHL}	Propagation Delay LE to O	2.0	6.7	ns	1, 5
t_{PZH} t_{PZL}	Output Enable Time	1.5	6.1	ns	1, 7, 8
t_{PHZ} t_{PLZ}	Output Disable Time	1.5	5.5	ns	1, 7, 8
t_{SU}	Set-Up Time HIGH or LOW, D to LE	2.0		ns	9
t_{H}	Hold Time HIGH or LOW, D to LE	1.5		ns	9
t_{W}	LE Pulse Width HIGH	3.3		ns	5
$t_{SK(O)}$	Output Skew[14]		0.5	ns	—

Parameter	Description	CY74FCT16373CT CY74FCT162373CT		Unit	Fig. No.[13]
		Min.	Max.		
t_{PLH} t_{PHL}	Propagation Delay D to O	1.5	4.2	ns	1, 3
t_{PLH} t_{PHL}	Propagation Delay LE to O	2.0	5.5	ns	1, 5
t_{PZH} t_{PZL}	Output Enable Time	1.5	5.5	ns	1, 7, 8
t_{PHZ} t_{PLZ}	Output Disable Time	1.5	5.0	ns	1, 7, 8
t_{SU}	Set-Up Time HIGH or LOW, D to LE	2.0		ns	9
t_{H}	Hold Time HIGH or LOW, D to LE	1.5		ns	9
t_{W}	LE Pulse Width HIGH	3.3		ns	5
$t_{SK(O)}$	Output Skew[14]		0.5	ns	—

Notes:
12. Minimum limits are specified but not tested on Propagation Delays.
13. See “Parameter Measurement Information” in the General Information section.
14. Skew between any two outputs of the same package switching in the same direction. This parameter is ensured by design.

Ordering Information CY74FCT16373

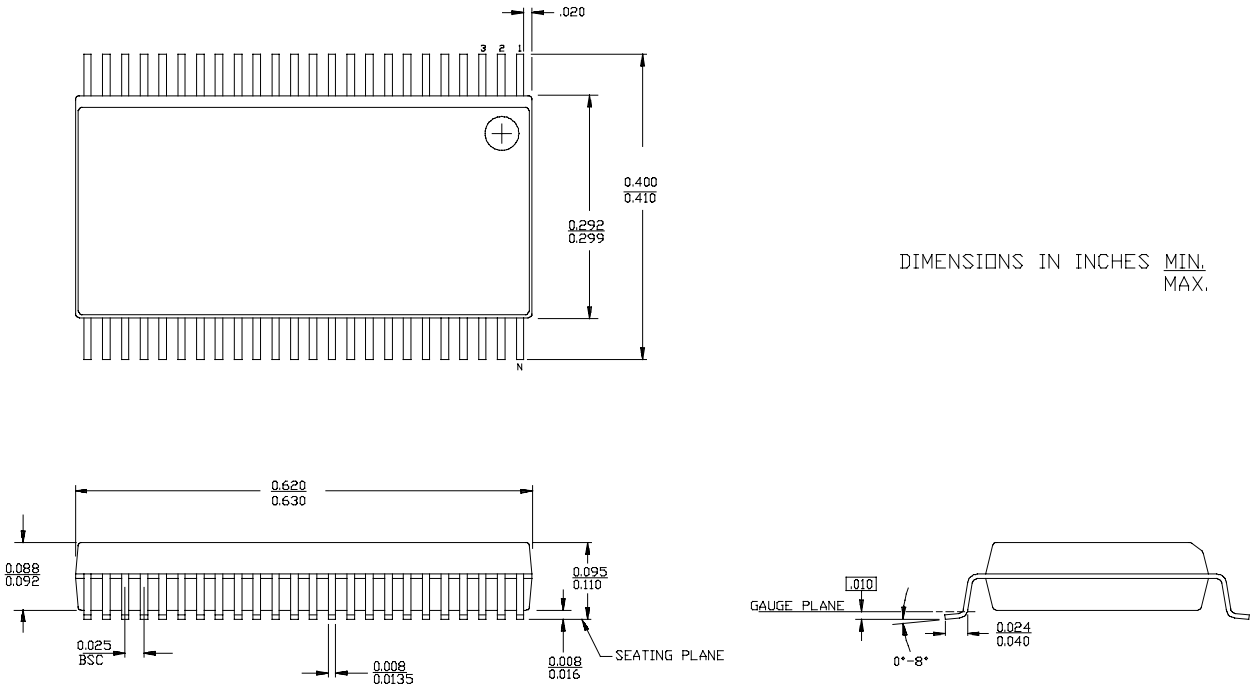
Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
4.2	CY74FCT16373CTPACT	Z48	48-Lead (240-Mil) TSSOP	Industrial
	CY74FCT16373CTPVC/PVCT	O48	48-Lead (300-Mil) SSOP	
	CY74FCT16373CTVR	-	48-Lead (173-Mil) TVSOP	
5.2	CY74FCT16373ATPACT	Z48	48-Lead (240-Mil) TSSOP	Industrial
	CY74FCT16373ATPVC/PVCT	O48	48-Lead (300-Mil) SSOP	
	CY74FCT16373ATVR	-	48-Lead (173-Mil) TVSOP	

Ordering Information CY74FCT162373

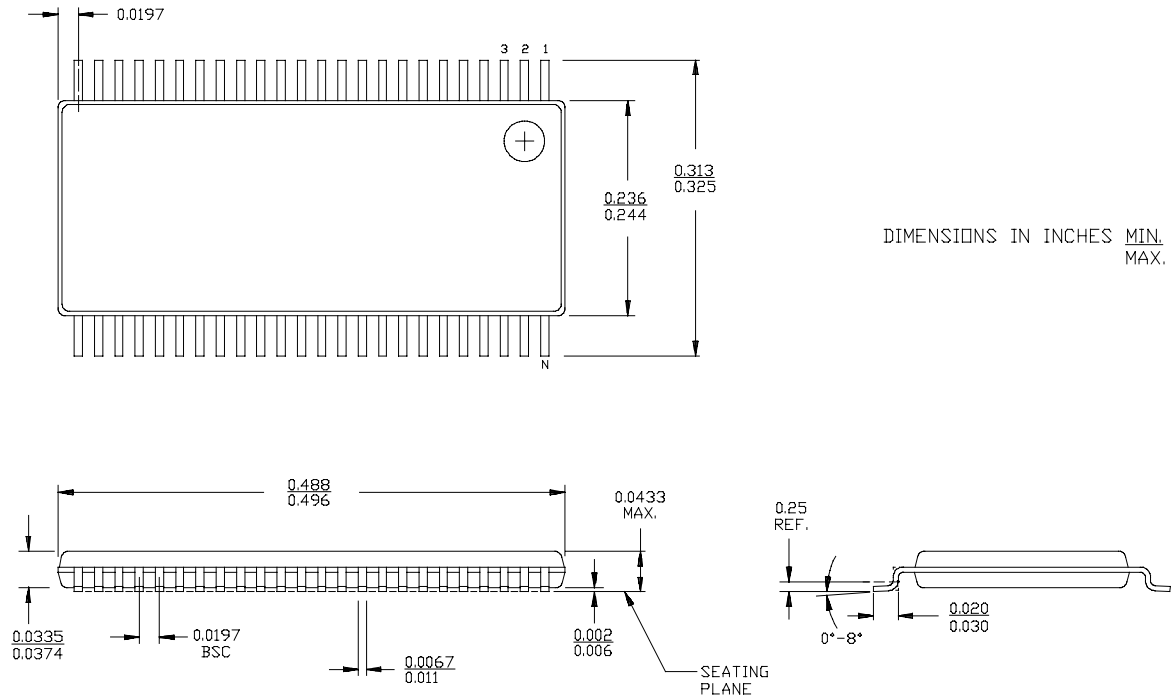
Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
4.2	74FCT162373CTPACT	Z48	48-Lead (240-Mil) TSSOP	Industrial
	CY74FCT162373CTPVC	O48	48-Lead (300-Mil) SSOP	
	74FCT162373CTPVCT	O48	48-Lead (300-Mil) SSOP	
5.2	74FCT162373ATPACT	Z48	48-Lead (240-Mil) TSSOP	Industrial
	CY74FCT162373ATPVC	O48	48-Lead (300-Mil) SSOP	
	74FCT162373ATPVCT	O48	48-Lead (300-Mil) SSOP	

Package Diagrams

48-Lead Shrunk Small Outline Package O48



48-Lead Thin Shrunk Small Outline Package Z48



PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
74FCT162373ATPACT	Obsolete	Production	TSSOP (DGG) | 48	-	-	Call TI	Call TI	-40 to 85	FCT162373A
74FCT162373ATPVCT	Obsolete	Production	SSOP (DL) | 48	-	-	Call TI	Call TI	-40 to 85	FCT162373A
CY74FCT162373ATPVC	Obsolete	Production	SSOP (DL) | 48	-	-	Call TI	Call TI	-40 to 85	FCT162373A
CY74FCT162373CTPVC	Obsolete	Production	SSOP (DL) | 48	-	-	Call TI	Call TI	-40 to 85	FCT162373C
CY74FCT16373ATPACT	Obsolete	Production	TSSOP (DGG) | 48	-	-	Call TI	Call TI	-40 to 85	FCT16373A
CY74FCT16373ATPVCT	Obsolete	Production	SSOP (DL) | 48	-	-	Call TI	Call TI	-40 to 85	FCT16373A
CY74FCT16373CTPACT	Obsolete	Production	TSSOP (DGG) | 48	-	-	Call TI	Call TI	-40 to 85	FCT16373C
CY74FCT16373CTPVC	Obsolete	Production	SSOP (DL) | 48	-	-	Call TI	Call TI	-40 to 85	FCT16373C

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

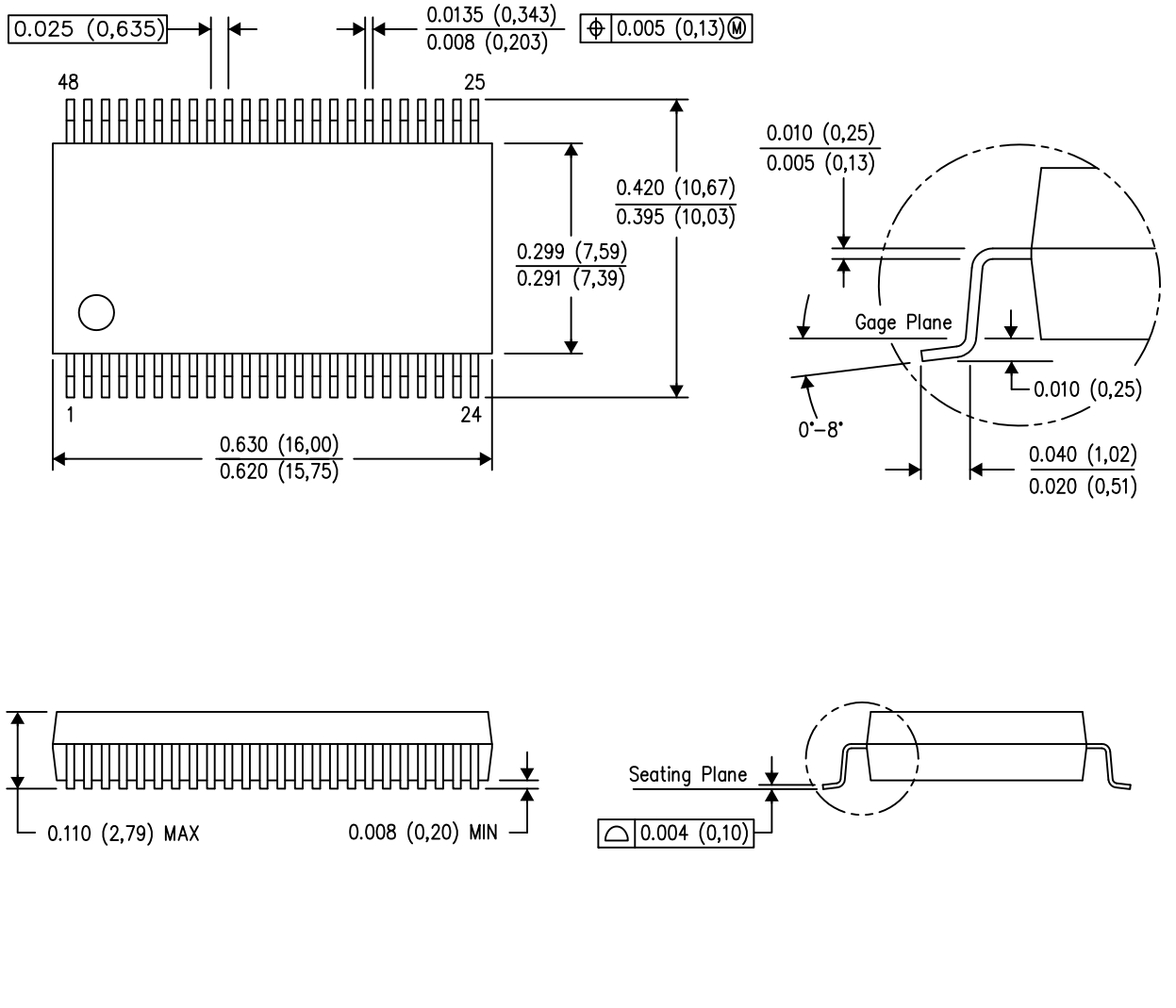
(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

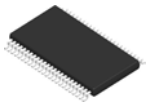
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

DL (R–PDSO–G48) PLASTIC SMALL–OUTLINE PACKAGE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MO–118

PowerPAD is a trademark of Texas Instruments.

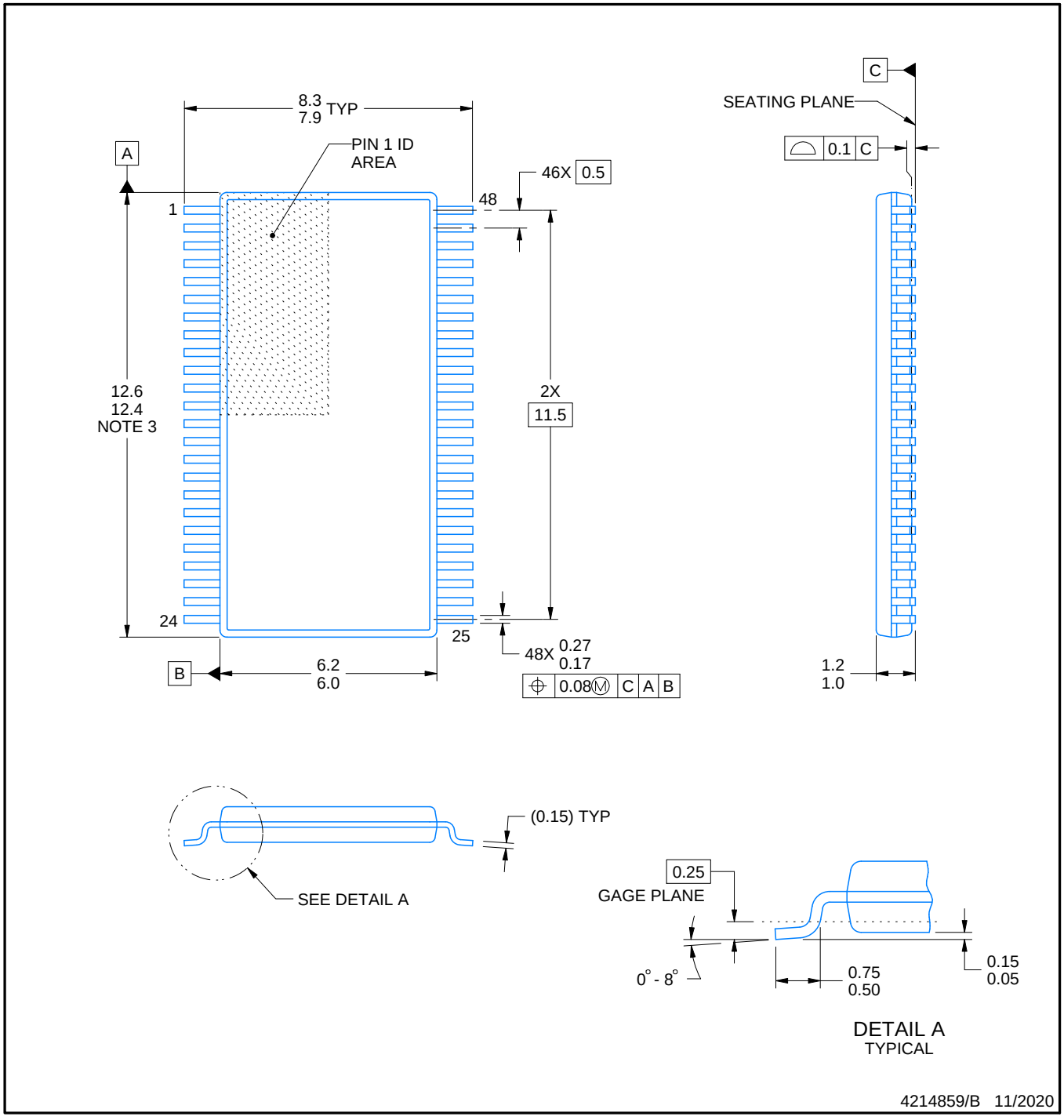


PACKAGE OUTLINE

DGG0048A

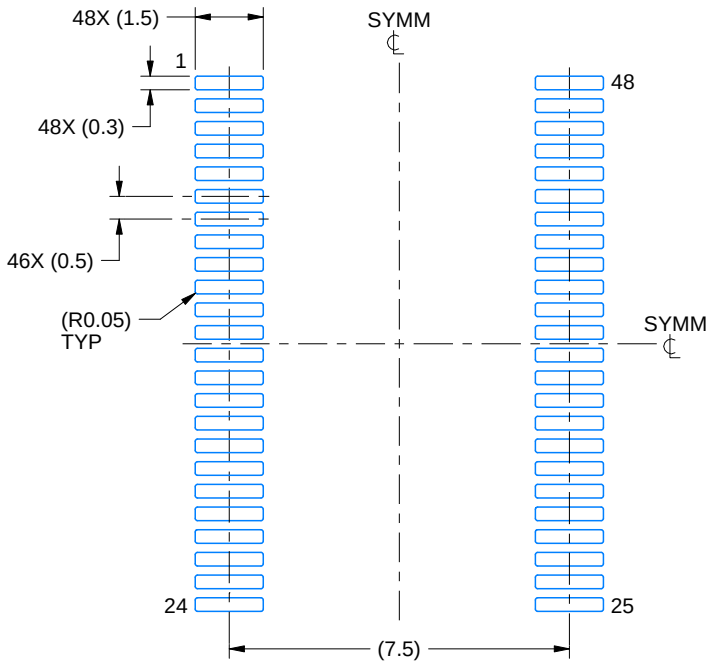
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

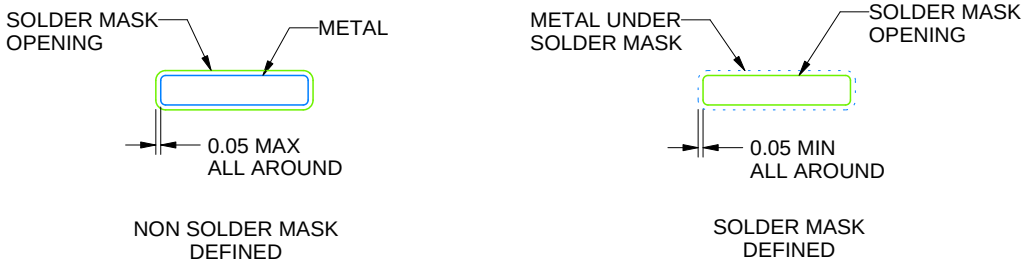


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-153.



LAND PATTERN EXAMPLE
SCALE:6X

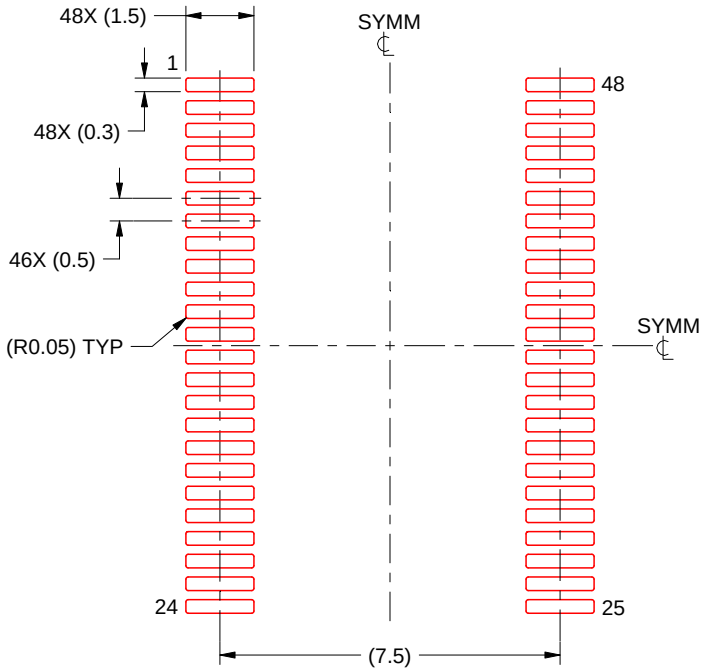


SOLDER MASK DETAILS

4214859/B 11/2020

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

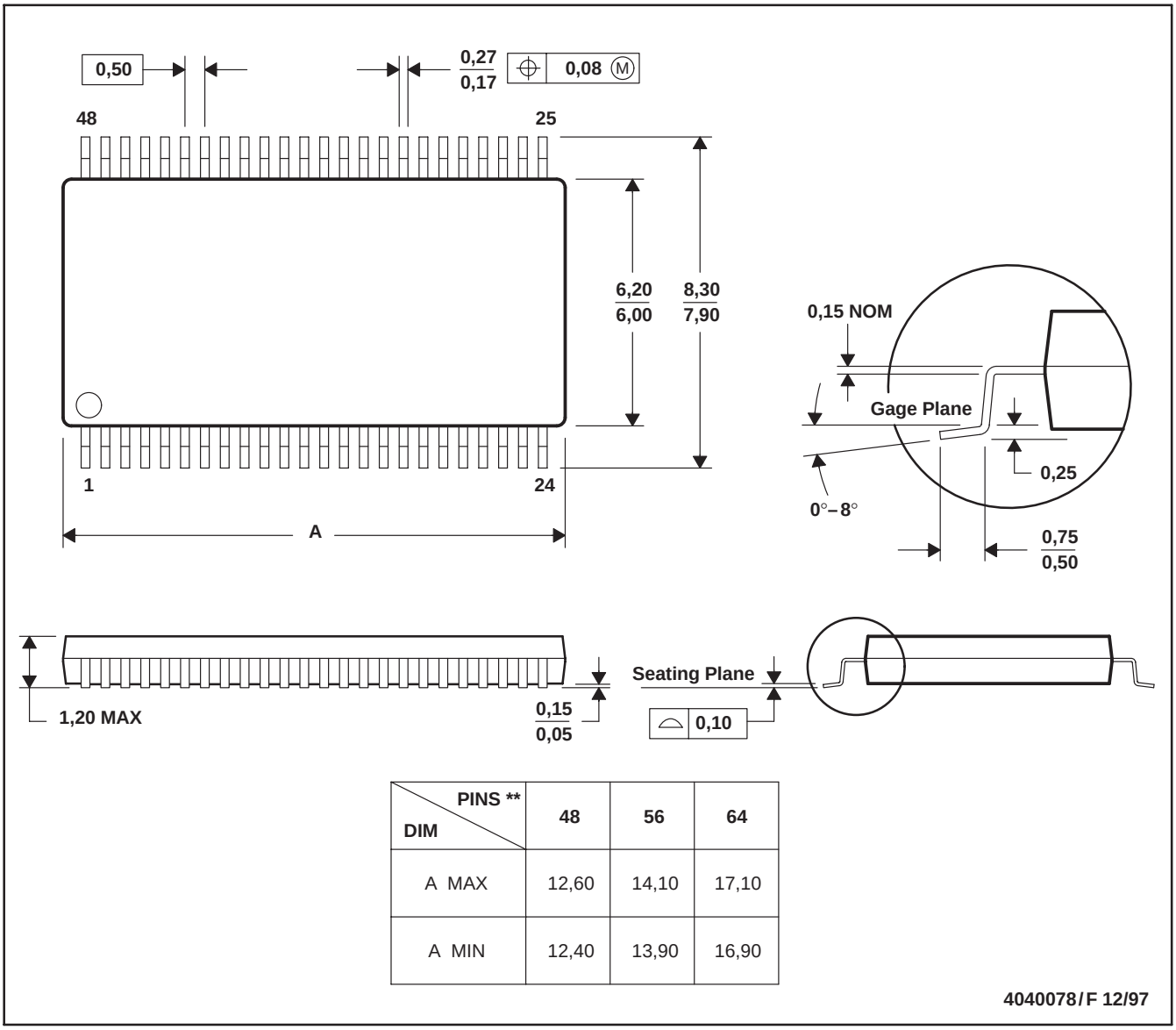
4214859/B 11/2020

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

DGG (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

48 PINS SHOWN



DIM \ PINS **	48	56	64
A MAX	12,60	14,10	17,10
A MIN	12,40	13,90	16,90

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold protrusion not to exceed 0,15.
D. Falls within JEDEC MO-153

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES “AS IS” AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you fully indemnify TI and its representatives against any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI’s products are provided subject to TI’s Terms of Sale, TI’s General Quality Guidelines, or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI’s provision of these resources does not expand or otherwise alter TI’s applicable warranties or warranty disclaimers for TI products. Unless TI explicitly designates a product as custom or customer-specified, TI products are standard, catalog, general purpose devices.

TI objects to and rejects any additional or different terms you may propose.

Copyright © 2025, Texas Instruments Incorporated

Last updated 10/2025